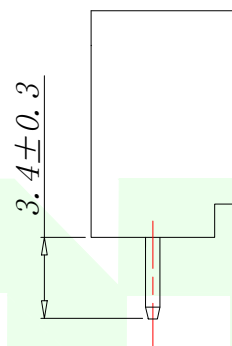
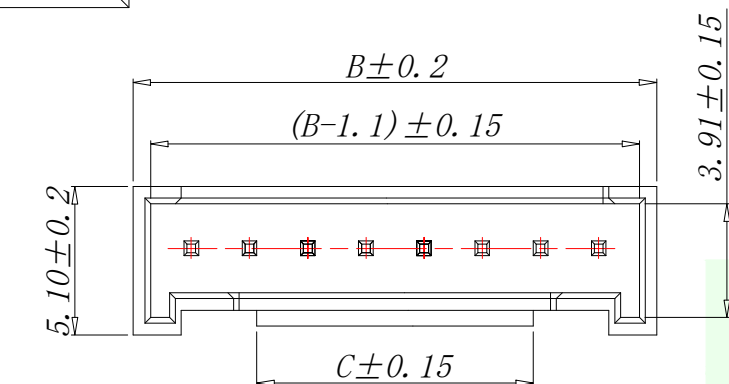


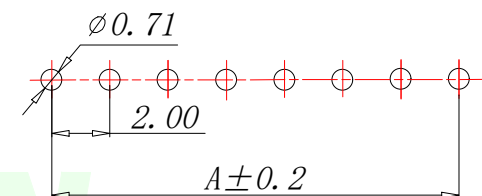
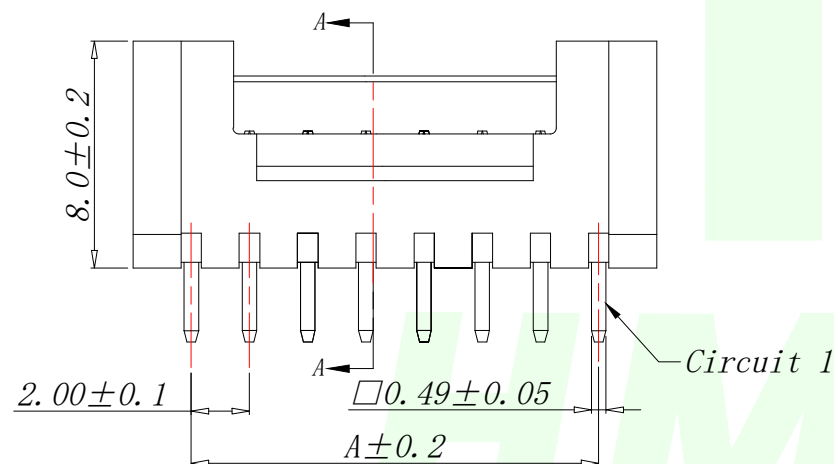
<i>VER</i>	<i>MARK</i>	<i>PR. BY</i>	<i>DESCRIPTTON</i>	<i>DATE</i>



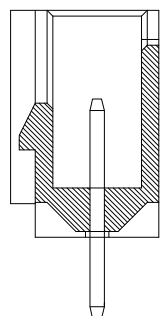
<i>PIN number variable size comparison table</i>				
<i>PART NO</i>	<i>PIN</i>	<i>A</i>	<i>B</i>	<i>C</i>
<i>HMT-HY2. 0-ZZ2P</i>	<i>2</i>	<i>2. 00</i>	<i>6. 00</i>	<i>2. 50</i>
<i>HMT-HY2. 0-ZZ3P</i>	<i>3</i>	<i>4. 00</i>	<i>8. 00</i>	<i>2. 50</i>
<i>HMT-HY2. 0-ZZ4P</i>	<i>4</i>	<i>6. 00</i>	<i>10. 00</i>	<i>3. 50</i>
<i>HMT-HY2. 0-ZZ5P</i>	<i>5</i>	<i>8. 00</i>	<i>12. 00</i>	<i>5. 50</i>
<i>HMT-HY2. 0-ZZ6P</i>	<i>6</i>	<i>10. 00</i>	<i>14. 00</i>	<i>7. 50</i>
<i>HMT-HY2. 0-ZZ7P</i>	<i>7</i>	<i>12. 00</i>	<i>16. 00</i>	<i>9. 50</i>
<i>.....</i>	<i>.....</i> <i>.</i>	<i>.....</i>	<i>.....</i>	<i>.....</i>
<i>HMT-HY2. 0-ZZ15P</i>	<i>15</i>	<i>28. 00</i>	<i>32. 00</i>	<i>15. 50</i>

技术要求:

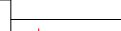
- | | |
|---|--------|
| 1. 塑件材料:PA66 (UL-94V-0) | HMT-HY |
| 2. 接触件:黄铜镀锡 | . |
| 3. 接触电阻: $\leq 10\text{m}\Omega$ | HMT-HY |
| 4. 绝缘电阻: $\geq 100\text{M}\Omega$ | |
| 5. 额定电压:250V AC DC | |
| 6. 额定电流:2.0A AC DC | |
| 7. 耐压:能承受1000V AC/Minute | |
| 8. 工作温度: $-25^{\circ}\sim +85^{\circ}$ | |
| 9. 可焊性试验:浸锡面积 $\geq 95\%$ 温度 235^{+5}_{-0} ,
时间 2.5 ± 0.5 秒 | |
| 10. 铅和镉等六大有害物质含量要符合
环保要求. | |



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



SECTION A-A

2	端子 Contact	黄铜	N*1	电镀(锡):整个表面镀底镍 30u~MIN, 再镀锡 80u~MIN	GENERAL TOLERANCES UNLESS SPECIFIED		深圳市华明通电子有限公司 HMTCONN Shenzhen Huamingtong Electronics Co., Ltd				
					X.X ±0.30	X.° ±5°	PART NO. HMT-HY2.0-ZZNP		TITLE: HY2.0MM 直针带扣		
1	基座 Wafer	PA66 (UL94V-0)	1	白色	.XX ±0.20	X.X° ±1°	DESIGN: James		CUSTOMER	SIZE	UNITS
					.XXX ±0.10	X.XX° ±0.5°	CHED: Talen			A4	MM
序号	名称	材料	数量	备注	MANUFACTURE DWG		APPD: Sophia			SCALE	SHEET
										N:A	1/1